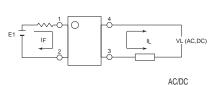
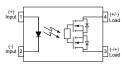
# **APSEMI®**

Parameter	Symbol	Rating	Units	
Load Voltage	VL	60	V	
Load Current	IL	0.8	Α	
On-Resistance	Ron	0.24	Ω	
I/O Isolation Voltage	V/ıo	2500	Vrms	





- LED Anode
- 2. LED Cathode
- 3.4. Drain(MOS FET)



### **APSEMI PhotoRelays**

- Long life (No limit on mechanical and electrical
- lifetime)Bounce-free switching
- Higher speed and high frequency switching
- Higher sensitivity (less power consumption)
- Immunity to EMI or RFI

- No have voltaic arc, bounce, and noise More
- · resistant to vibration and impact AC or DC load
- switching
- Small package size

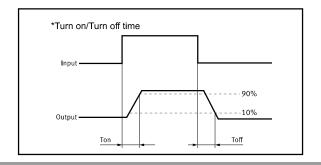
## **Applications**

- Telecom/Datacom switching
- Multiplexers
- Meter reading systems
- Data acquisition
- Medical equipment
- Battery monitoring
- I/O Sub-Systems

- Robotics
- Aerospace
- Home/Safety security systems
- Process Control
- Energy Management
- Reed Relay EMR Replacement
- Programmable Controllers

### **TPYES**

Catagoni	Output Rating		Doolsono	Part No.	Packing Overtity	
Category	Load Voltage	Load Current	Package	Part No.	Packing Quantity	
AC/DC	60V	0.8A	SOP-4	GAQY212GS	2000pcs /reel	





# Absolute Maximum Ratings (Ta = 25°C)

	Item	Symbol	Value	Units	Note
Continuous LED Current		l <sub>F</sub>	50	mA	
Input	Peak LED Current	<b>I</b> FP	1000	mA	f=100Hz, duty=1%
	LED Reverse Voltage	VR	5	V	
	Input Power Dissipation	P <sub>In</sub>	75	mW	
Output L	Load Voltage	VL	60	V(AC peak or DC)	
	Load Current	lι	0.8	Α	
	Peak Load Current	Peak	1.5	Α	100ms(1 pulse)
	Output Power Dissipation	Pout	450	mW	
Total Powe	er Dissipation	Рт	500	mW	
I/O Breakd	lown Voltage	V <sub>I/O</sub>	2500	Vrms	RH=60%, 1min
Operating	Temperature	Topr	-40 to +85	°C	
Storage Te	emperature	T <sub>stg</sub>	-40 to +100	°C	
Pin Solder	ing Temperature	T <sub>sol</sub>	260	°C	10 sec max.

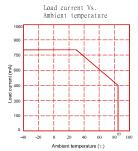
Electrical Specifications (Ambient Temperature: 25°C)

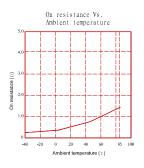
	Item	Symbol	MIN.	TYP.	MAX.	Units	Conditions
	LED Forward Voltage	VF		1.32	1.5	V	I⊧=10mA
Input	Operation LED Current	<b>I</b> F on		0.8	2.0	mA	
	Recovery LED Current	<b>I</b> F off		0.35	0.5	mA	
	Recovery LED Voltage	V <sub>F</sub> off	0.7			V	
Output	On-Resistance	Ron		0.24	0.6	Ω	I⊧=5mA,I∟=Max Time to flow is within 1 sec.
·	Off-State Leakage Current	I <sub>Leak</sub>		0.1		uA	V <sub>L</sub> =Rating
	Output Capacitance	Cout		28		pF	V∟=0, f=1MHz
Transmis	Turn-On Time	Ton		0.35	0.5	ms	I⊧=5mA, I∟=Max
sion	Turn-Off Time	Toff		0.1	0.3	ms	
Coupled	I/O Isolation Resistance	Rı/o	1010			GΩ	DC500V
Coupled	I/O Capacitance	C <sub>1/O</sub>		0.8	1.5	pF	f=1MHz

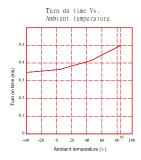
Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value): IF ≥5mA and ≤30mA

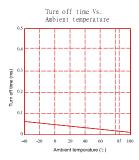
# **APSEMI®**

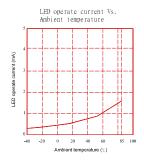
## **Engineering Data**

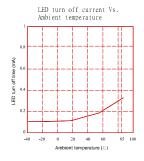


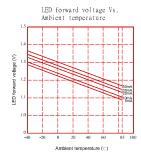


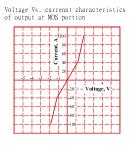


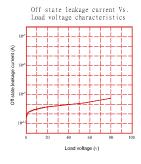


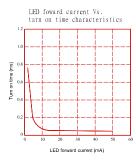


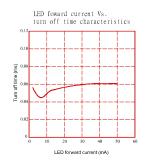


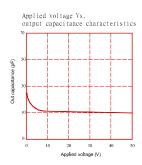










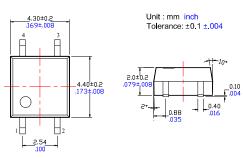


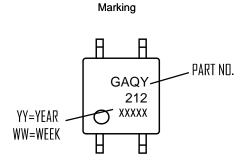
# **APSEMI®**

# **Dimensions and Package**

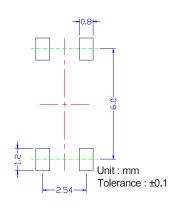
# 0.66±0.2 0.26±0.08 0.36 0.36 0.36 0.36

# Surface mount terminal type

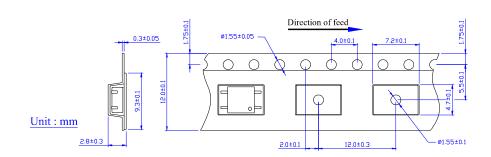




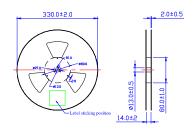
# Recommended mounting pad (Top view)

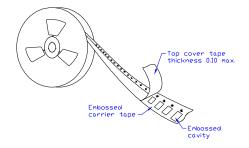


## Tape dimensions



### Dimensions of tape reel

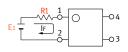


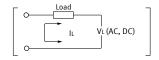




## **Using Methods**

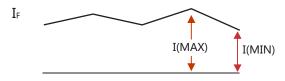
Examples of resistance value to control LED forward current (IF=5mA)





E1	R1 (Approx)
3.3V	300 Ω
5.0V	600 Ω
12V	1.9KΩ
24V	4.1K Ω

LED forward current must be more than 5mA, at I(MIN), and less than 30mA, at I(MAX).



### **Recommended Operating Conditions**

Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value):

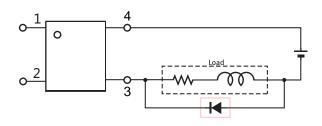
Characteristic	Symbol	Min	Тур.	Max	Unit
Forward current	l <sub>F</sub>	5.0	7.0	30	mA

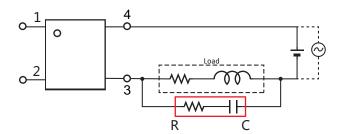
### **Protection Circuit**

Output spike voltages:if an inductive load generates spike voltages which exceed heabsolute maximum rating, the spike voltage shall be limited.

Clamp diode is connected in parallel with the load. Absorb capacity with external diode.

CR Snubber is connected in parallel with the load. Absorb capacity with buffer capacity.





When adding diodes, buffer circuits (C-R), and other protections, they need to be installed near the MOS RELAY to be effective. Adding protection elements may result in a slow reset time, so adjust them according to the actual situation before use.

Note: When developing designs using this product, perform the expected performance of the equipment under the operating conditions recommended by the guidelines in this document. Continuous use under heavy loads (including, but not limited to, the application of high temperatures/current/voltage and significant changes in temperature, etc.) may result in deterioration of the reliability of this product.